

Title (en)

METHOD AND APPARTUS FOR HIGH VOLUME ASSEMBLY OF RADIO FREQUENCY IDENTIFICATION TAGS

Title (de)

VERFAHREN UND VORRICHTUNG ZUR HOCHVOLUMIGEN ANORDNUNG VON HOCHFREQUENZ-IDENTIFIKATIONSETIKETTEN

Title (fr)

PROCEDE ET DISPOSITIF POUR ASSEMBLAGE A HAUT DEBIT D'ETIQUETTES D'IDENTIFICATION RADIOFREQUENCE

Publication

EP 1545828 A4 20080723 (EN)

Application

EP 03766981 A 20030730

Priority

- US 0323792 W 20030730
- US 40010102 P 20020802
- US 32246702 A 20021219
- US 32271802 A 20021219
- US 32270102 A 20021219
- US 32270202 A 20021219
- US 42980303 A 20030506

Abstract (en)

[origin: WO2004012896A1] A plurality of electrical devices, such as RFID tags, that each include a die having one or more connecting pads, are produced. Dies are transferred from a wafer directly to substrates, or from the wafer to one or more intermediate surfaces before being transferred to the substrates. Dies can be transferred between surfaces using an adhesive surface mechanism and process. Dies can be alternatively transferred between surfaces using a punching mechanism and process. Dies can be alternatively transferred between surfaces using a multi-barrel die collet mechanism and process. Alternatively, a die frame is formed. Furthermore, dies are transferred using the die frame.

IPC 1-7

B23P 19/00; **H05K 3/30**

IPC 8 full level

B42D 15/10 (2006.01); **G06K 19/07** (2006.01); **G06K 19/077** (2006.01); **H01L 21/56** (2006.01); **H01L 21/60** (2006.01); **H01L 21/68** (2006.01); **H01L 23/12** (2006.01); **H05K 3/30** (2006.01)

CPC (source: EP)

G06K 19/07718 (2013.01); **G06K 19/07745** (2013.01); **G06K 19/07749** (2013.01); **G06K 19/0775** (2013.01); **G06K 19/07758** (2013.01); **H01L 21/56** (2013.01); **H01L 21/6835** (2013.01); **H01L 24/96** (2013.01); **H01L 2221/68313** (2013.01); **H01L 2221/68322** (2013.01); **H01L 2221/68354** (2013.01); **H01L 2224/16** (2013.01); **H01L 2224/16225** (2013.01); **H01L 2224/16227** (2013.01); **H01L 2224/81191** (2013.01); **H01L 2224/83191** (2013.01); **H01L 2924/01005** (2013.01); **H01L 2924/01006** (2013.01); **H01L 2924/01013** (2013.01); **H01L 2924/01015** (2013.01); **H01L 2924/01027** (2013.01); **H01L 2924/01033** (2013.01); **H01L 2924/01047** (2013.01); **H01L 2924/01057** (2013.01); **H01L 2924/01074** (2013.01); **H01L 2924/01077** (2013.01); **H01L 2924/01079** (2013.01); **H01L 2924/01082** (2013.01); **H01L 2924/09701** (2013.01); **H01L 2924/12042** (2013.01); **H01L 2924/14** (2013.01); **H01L 2924/19041** (2013.01); **H01L 2924/19042** (2013.01); **H01L 2924/19043** (2013.01)

Citation (search report)

- [X] WO 0176949 A2 20011018 - MELZER MASCHINENBAU GMBH [DE], et al
- [A] WO 0161646 A1 20010823 - MOORE NORTH AMERICA INC [US]
- [A] US 5255430 A 19931026 - TALLAKSEN KENT A [US], et al
- See references of WO 2004012896A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

Designated extension state (EPC)

AL

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DOCDB simple family (application)

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